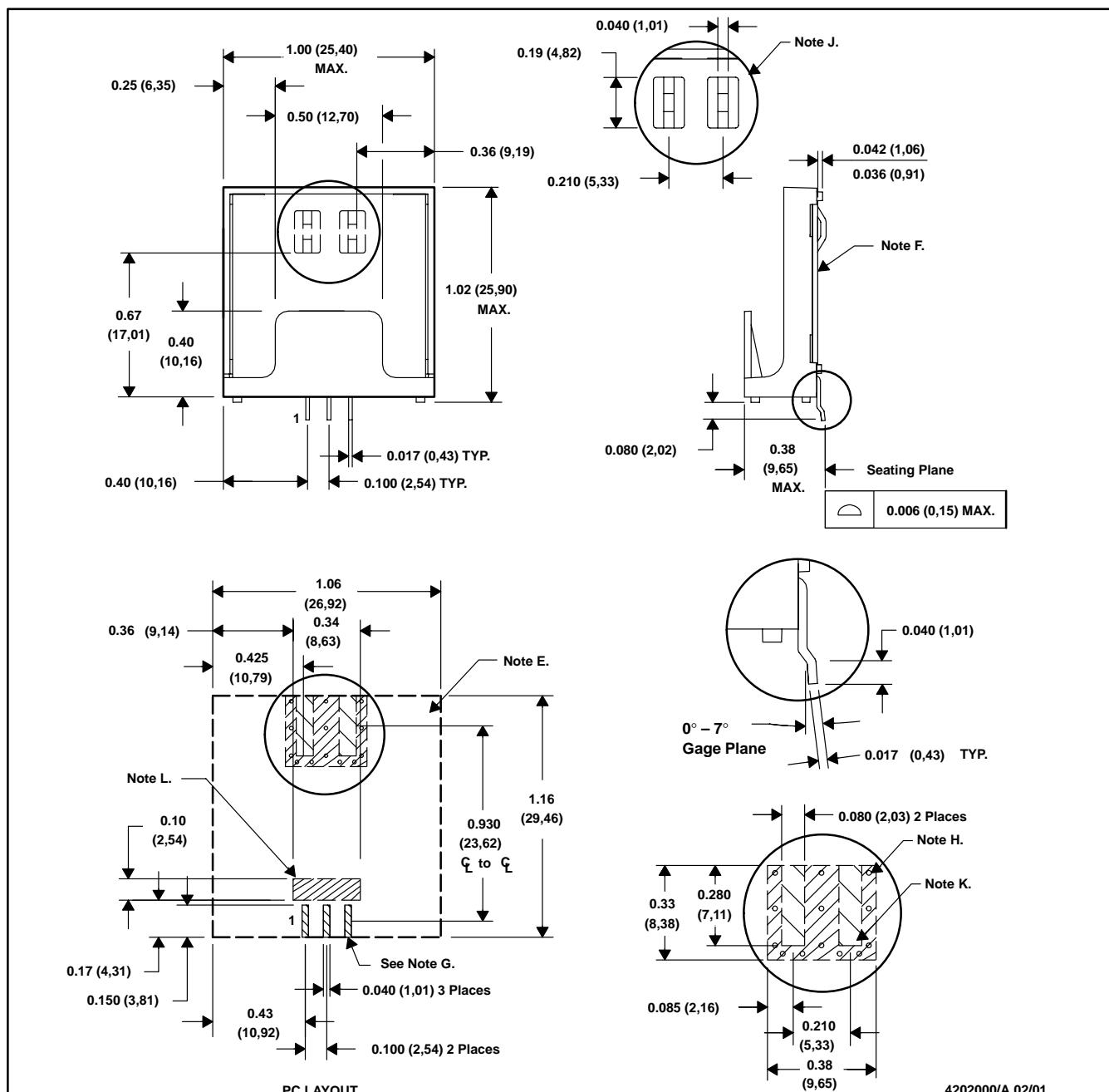


## EAL (R-PSIP-G3)

## PLASTIC SINGLE-IN-LINE MODULE



NOTES:

- A. All linear dimensions are in inches (mm).
- B. This drawing is subject to change without notice.
- C. 2-place decimals are  $\pm 0.030$  ( $\pm 0.76$  mm).
- D. 3-place decimals are  $\pm 0.010$  ( $\pm 0.25$  mm).
- E. Recommended mechanical keep-out area.
- F. The metal tab is isolated but electrically conductive.  
No signal traces are allowed under the metal tab area.  
A solid copper island is recommended, which may be grounded.
- G. Power pin connections should utilize two or more vias per input, ground and output pin.

- H. Minimum copper land area required for solder tab.  
Vias are recommended to improve copper adhesion or connect land to other ground area.
- J. Underside solder tabs detail.
- K. Solder mask openings to copper island for solder joints to mechanical pins.
- L. No copper, power or signal traces in this area.

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